MA2S374

Silicon epitaxial planar type

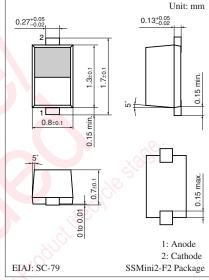
For CATV tuner

Features

- Small series resistance r_D
- SS-Mini type package, allowing downsizing of equipment and automatic in

automatic insertion through Absolute Maximum Ra	1 01			
Parameter	Symbol	Rating	Unit	
Reverse voltage	V _R	34	V	
Maximum peak reverse voltage *	V _{RM}	35	V	
Junction temperature	Tj	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

Note) *: $R_L = 10 k\Omega$



Marking Symbol: T

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current	IR	$V_R = 30 V$	00	SOL	10	nA
Diode capacitance	C _{D(0V)} *1	$V_R = 0 V, f = 1 MHz$	87	0		pF
	C _{D(2V)}	$V_R = 2 V, f = 1 MHz$	44.00		50.79	
	C _{D(25V)}	$V_{R} = 25 V, f = 1 MHz$	2.60		3.03	
	C _{D(10V)}	$V_{R} = 10 V, f = 1 MHz$	8.80		13.08	
all'an	C _{D(17V)}	$V_{R} = 17 V, f = 1 MHz$	3.70		5.04	
Capacitance ratio	C _{D(2V)} /C _{D(25V)}	ist when	15.0			_
Diode capacitance deviation	ΔC	C _{D(2V)(10V)(17V)(25V)}			2.0	%
Series resistance *2	r _D	$C_{\rm D} = 9 \text{ pF}, \text{ f} = 470 \text{ MHz}$			0.9	Ω

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

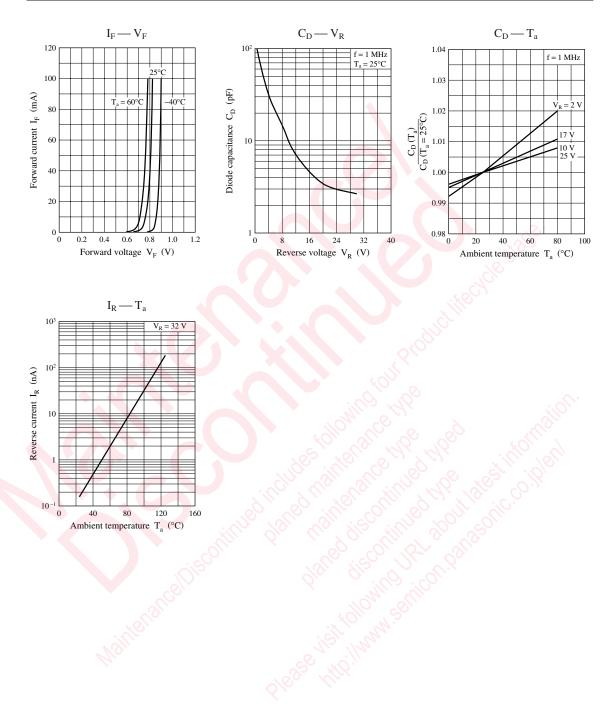
2. Absolute frequency of input and output is 470 MHz.

3. *1: Measurement at low signal level

*2: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER

MA2S374





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